

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended): An electronic substrate ~~[[5]]~~ suitable for being included in a stack ~~containing~~ including said electronic substrate and ~~at least one other~~ another electronic substrate and suitable for being connected to the other electronic substrate~~[[s]]~~ and ~~optionally~~ to an input-output interface ~~[[31]]~~, ~~characterized in that it comprises~~ comprising:

a frame ~~[[10]]~~ consisting made of a material with a high thermal conductivity ~~comprising~~ having a plurality of sides, ~~at least one~~ a first side ~~[[11]]~~ of which is intended to be in contact with ~~[[the]]~~ a corresponding side of the frame of another ~~(or the other)~~ neighboring substrate~~[[s]]~~ so as to provide thermal dissipation of the electronic substrates and ~~at least one~~ a second side ~~[[12]]~~ of which comprises an interconnection element ~~[[120]]~~ intended to provide electrical interconnection between said electronic substrate ~~[[5]]~~ and the other electronic substrate~~[[s]]~~ by means of a routing circuit ~~[[121]]~~ suitable for being matched ~~and/or~~ modified according to the electrical interconnection and/or between said electronic substrate ~~[[5]]~~ and the input-output interface ~~[[31]]~~.

2. (currently amended): The electronic substrate as claimed in ~~the preceding~~ claim 1, ~~characterized in that~~ wherein the frame ~~[[10]]~~ has a bottom ~~[[13]]~~ ~~also consisting~~ of a material with a high thermal conductivity.

3. (currently amended): The electronic substrate as claimed in ~~the preceding~~ claim 1, ~~characterized in that~~ wherein the bottom ~~[[13]]~~ includes a phase-change cooling element ~~[[14]]~~.

4. (currently amended): The electronic substrate as claimed in ~~any one of the preceding~~ claim~~[[s]]~~ 1, ~~characterized in that~~ wherein said electronic substrate ~~[[5]]~~ has

conductive tracks $[(53)]$ and in that the interconnection element $[(120)]$ includes a first conductive element $[(125')]$ intended to be in contact with the tracks $[(53)]$.

5. (currently amended): The electronic substrate as claimed in ~~the preceding~~ claim 4, ~~characterized in that~~ wherein the interconnection element $[(120)]$ also includes a second conductive element $[(125'')]$ intended to be connected to the routing circuit $[(121)]$ with a view to connecting this second conductive element $[(125'')]$ to ~~at least one~~ a conductive element of the interconnection element of the frame of the other neighboring electronic substrate $[(s)]$.

6. (currently amended): The electronic substrate as claimed in ~~either one of~~ claim $[(s)]$ 4 ~~and 5~~, ~~characterized in that~~ wherein the conductive element ~~(125' and/or 125'')~~ comprises conductive rings $[(122)]$ inserted between two insulators $[(123)]$.

7. (currently amended): The electronic substrate as claimed in ~~any one of the preceding~~ claim $[(s)]$ 1, ~~characterized in that~~ wherein the routing circuit $[(121)]$ is a multilayer printed circuit.

8. (currently amended): The electronic substrate as claimed in ~~any one of the preceding~~ claim $[(s)]$ 1, ~~characterized in that~~ wherein the frame $[(10)]$ includes reversible positioning means ~~(15, 16)~~ intended to position said frame $[(10)]$ with respect to the frame of the other neighboring electronic substrate and/or with respect to the input-output interface $[(31)]$.

9. (currently amended): The electronic substrate as claimed in ~~the preceding~~ claim 8, ~~characterized in that~~ wherein the reversible positioning means include first centering pins $[(15)]$ and reinforcements $[(16)]$.

10. (currently amended): The electronic substrate as claimed in ~~any one of the preceding~~ claim[[s]] 1, ~~characterized in that~~ wherein the frame [[(10)]] includes second centering pins intended to position said substrate [[(5)]] in its frame [[(10)]].

11. (currently amended): The electronic substrate as claimed in ~~any one of the preceding~~ claim[[s]] 1, ~~characterized in that~~ wherein the substrate [[(5)]] is fixed to its frame [[(10)]] by means of an adhesive.

12. (currently amended): The electronic substrate as claimed in ~~any one of the preceding~~ claim[[s]], ~~characterized in that~~ wherein the material with a high conductivity is aluminum or copper or graphite.

13. (currently amended): The electronic substrate as claimed in ~~any one of the preceding~~ claim[[s]] 1, ~~characterized in that~~ wherein the substrate [[(5)]] includes a support [[(52)]] made of epoxy or ceramic or gallium arsenide or of a metallized insulator.

14. (currently amended): The electronic substrate as claimed in ~~any one of the preceding~~ claim[[s]] 1, ~~characterized in that~~ wherein the frame [[(10)]] has ~~at least for~~ four sides and in that two first sides [[(11)]] are intended for the thermal dissipation and two second sides [[(12)]] each include an interconnection element [[(120)]].

15. (currently amended): The electronic substrate as claimed in ~~any one of the preceding~~ claim[[s]] 1, ~~characterized in that~~ wherein it has a surface area of approximately 5 X 5 cm².

16. (currently amended): An electronic module [[(100)]] having an input-output interface [[(31)]] and a stack of a plurality of electronic substrates [[(5)]] as claimed in ~~any one of~~ claim[[s]] 1 to 15.

17. (currently amended): The electronic module as claimed in ~~the preceding~~ claim 16, ~~characterized in that~~ wherein it furthermore has a package ~~[(20)]~~ suitable for holding the stack of framed electronic substrates ~~[(5)]~~.

18. (currently amended): The electronic module as claimed in ~~either one of~~ claim~~[[s]]~~ 16 and 17, ~~characterized in that~~ wherein it includes a cover ~~[(30)]~~ comprising the input-output interface ~~[(31)]~~.

19. (currently amended): The electronic module as claimed in claim 17 taken in combination with claim 18, ~~characterized in that~~ wherein ~~[[the]]~~ cover ~~[(20)]~~ ~~includes~~ including means ~~[(40)]~~ for fastening to the package ~~[(20)]~~ and in that the fastening means ~~[(40)]~~ are suitable for stabilizing the framed substrates ~~[(5)]~~ in the package ~~[(20)]~~.

20. (currently amended): The electronic module as claimed in ~~the preceding~~ claim 19, ~~characterized in that~~ wherein the fastening means ~~[(40)]~~ are reversible.

21. (currently amended): The electronic module as claimed in ~~any one of~~ claim~~[[s]]~~ 17 to 20, ~~characterized in that~~ wherein the package ~~[(20)]~~ consists of a material with a high thermal conductivity.

22. (currently amended): The electronic module as claimed in ~~any one of~~ claim~~[[s]]~~ 17 to 20, ~~characterized in that~~ wherein the package has a specific interior profile and in that each frame has an exterior profile complementary to that of the package, with a view to facilitating pre-positioning of the frames in the package.